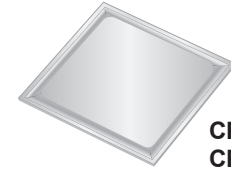


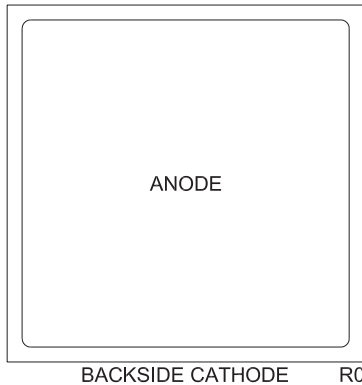
CPD31X CPD34X

10A, 60V

Schottky Rectifier Die



CPD31X
CPD34X



Die Size	85 MILS x 85 MILS
Die Thickness	5.9 MILS ±0.8 MILS
Die Passivation	SiN
Anode Bonding Pad Area	78 MILS x 78 MILS
Top Side Metalization (CPD31X)	Al/Ni/Au - 30,000Å/4,000Å/1,500Å
Top Side Metalization (CPD34X)	Al - 30,000Å
Back Side Metalization	Ti/Ni/Au - 1,600Å/5,550Å/1,500Å
Scribe Alley Width	3.15 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	2,260

Features:

- Low forward voltage at 10 Amps forward current
- Low reverse leakage current
- Low profile geometry
- Metalization suitable for standard die attached technologies
- Top metalization optimized for solder process (CPD31X)
- Top metalization optimized for wire bonding (CPD34X)

Applications:

- Optimized for use as a by-pass rectifier in low profile solar (PV) panels
- Reverse polarity protection
- OR-ing diode

Benefits:

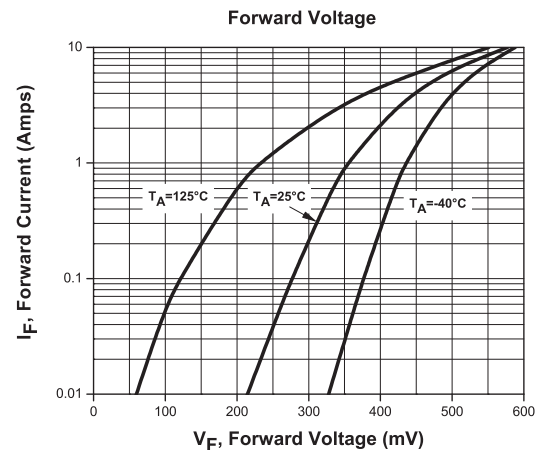
- Energy efficiency
- High temperature characterization
- Space savings

Literature

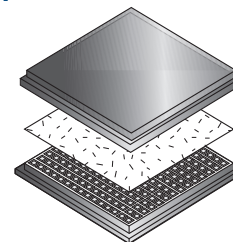


To order the latest Chip databook, visit:
web.centralsemi.com/search/sample.php

Typical Electrical Characteristics



Samples



To order samples contact:
Central's Sales department
631-435-1110

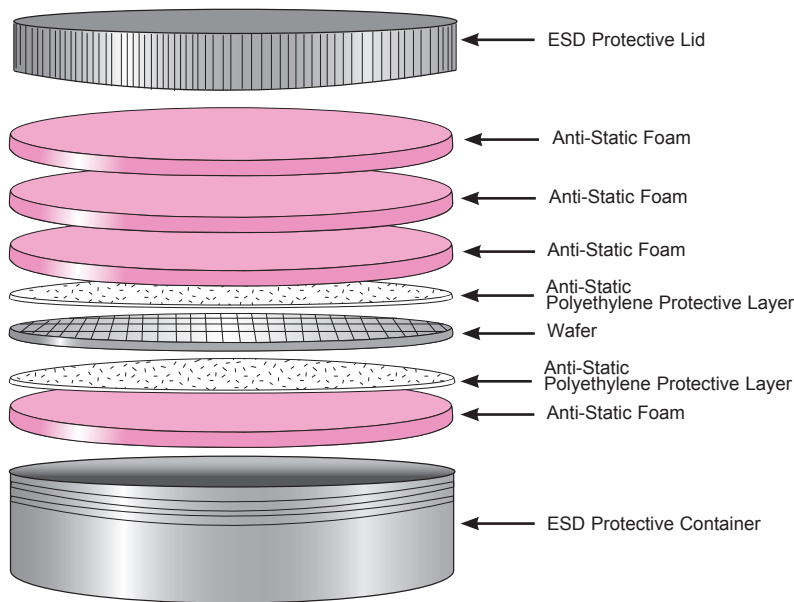
Maximum Ratings ($T_A = 25^\circ\text{C}$)					Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
V_{RRM}	V_R	I_O	I_{FSM}	T_J, T_{stg}	BVR	V_F		@ I_F	I_R		@ V_R
(V)	(V)	(A)	(A)	($^\circ\text{C}$)	(V)	(V)	(V)	(A)	TYP	MAX	(V)
MAX	MAX	MAX	MAX	MAX	MIN	TYP	MAX				MAX
60	60	10	250	-65 to +150	60	0.49	-	5.0	75 μA	500 μA	60
						0.59	0.67	10	-	*50mA	*60

* $T_A = 100^\circ\text{C}$

Packing Information

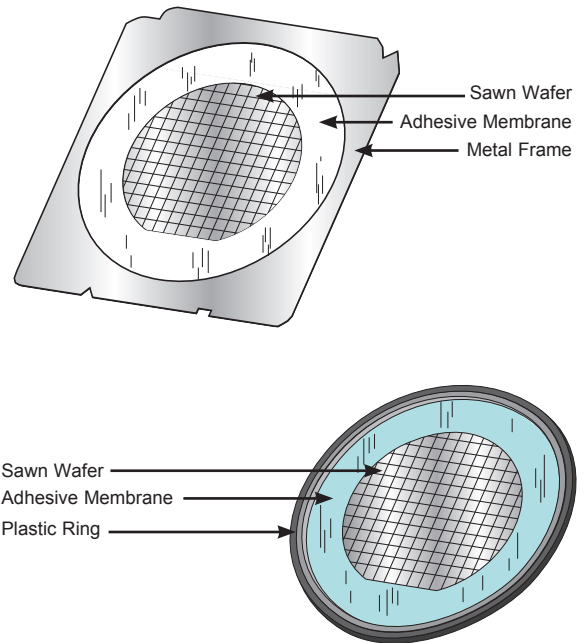
Wafer Form

- 100% tested with rejects inked
- Use - WN suffix when ordering



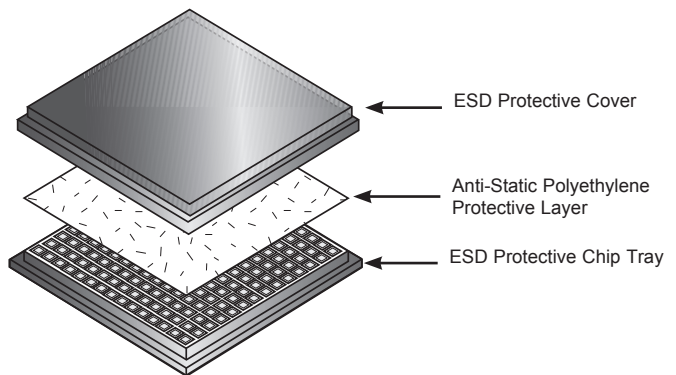
Sawn Wafer

- Available on metal frame or plastic ring
- 100% tested with rejects inked.
- Mounted on adhesive membrane on a metal frame or plastic ring.
- Use - WS suffix when ordering for metal frame
- Use - WR suffix when ordering for plastic ring.



Chip Form

- Waffle Packed.
- Use: **-CT**, **-CM**, **-CTO** suffix when ordering.
 - **-CT** (100% tested with rejects removed).
 - **-CM** (100% tested and 100% visually inspected per MIL-STD-750, [method 2072 transistors] [method 2073 diodes] with rejects removed).
 - **-CTO** (100% tested with rejects removed, die orientation as specified by customer.)



**Innovative Discrete
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